



N- and P-Channel 12-V (D-S) MOSFET

PRODUCT SUMMARY									
	V _{DS} (V)	$R_{DS(on)}(\Omega)$	I _D (A)	Q _g (Typ.)					
	12	0.029 at $V_{GS} = 4.5 \text{ V}$	4.5 ^a						
N-Channel		0.034 at $V_{GS} = 2.5 \text{ V}$	4.5 ^a	5.6 nC					
N-Channel		0.044 at V _{GS} = 1.8 V	4.5 ^a	5.6110					
		0.065 at V _{GS} = 1.5 V	4.5 ^a						
	- 12	0.061 at $V_{GS} = -4.5$ V	- 4.5 ^a						
P-Channel		0.081 at $V_{GS} = -2.5 \text{ V}$	- 4.5 ^a	8.2 nC					
		0.115 at $V_{GS} = -1.8 \text{ V}$	- 4.5 ^a	0.2110					
		0.170 at $V_{GS} = -1.5 \text{ V}$	- 4.5 ^a						

FEATURES

- TrenchFET® Power MOSFETs
- Thermally Enhanced PowerPAK® SC-70 Package
 - Small Footprint Area
 - Low On-Resistance
- Material categorization: For definitions of compliance please see www.vishay.com/doc?99912

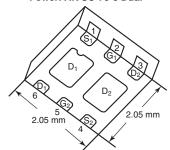


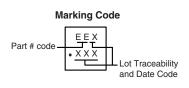
COMPLIANT HALOGEN FREE

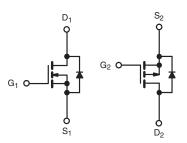
APPLICATIONS

Load Switch for Portable Devices

PowerPAK SC-70-6 Dual







Ordering Information: SiA517DJ-T1-GE3 (Lead (Pb)-free and Halogen-free)

N-Channel MOSFET P-Channel MOSFET

Parameter		Symbol	N-Channel	P-Channel	Unit	
Drain-Source Voltage		V_{DS}	12	- 12	V	
Gate-Source Voltage		V _{GS}	±	V		
	T _C = 25 °C		4.5 ^a	- 4.5 ^a		
Continuous Drain Current (T ₁ = 150 °C)	T _C = 70 °C	I _D	4.5 ^a	- 4.5 ^a		
Continuous Drain Current (1) = 150 °C)	T _A = 25 °C		4.5 ^{a, b, c}	- 4.3 ^{b, c}	A	
	T _A = 70 °C		4.5 ^{a, b, c}	- 3.8 ^{b, c}		
Pulsed Drain Current	•	I _{DM}	20 - 15			
Source Drain Current Diode Current	T _C = 25 °C	1	4.5 ^a	- 4.5 ^a]	
Source Drain Current Diode Current	T _A = 25 °C	I _S	1.6 ^{b, c}	- 1.6 ^{b, c}		
	T _C = 25 °C		6.5	6.5		
Marrian va Darray Dissipation	T _C = 70 °C		5	5		
Maximum Power Dissipation	T _A = 25 °C	P_{D}	1.9 ^{b, c}	1.9 ^{b, c}	W	
	T _A = 70 °C		1.2 ^{b, c}	1.2 ^{b, c}		
Operating Junction and Storage Temperature Ra	ange	T _J , T _{stg}	- 55 to 150		°C	
Soldering Recommendations (Peak Temperature	e) ^{d, e}		26			

THERMAL RESISTANCE RATINGS									
		N-Ch	annel	P-Ch	annel				
Parameter	Symbol	Тур.	Max.	Тур.	Max.	Unit			
Maximum Junction-to-Ambient ^{b, f}	t ≤ 5 s	R_{thJA}	52	65	52	65	°C/W		
Maximum Junction-to-Case (Drain)	Steady State	R_{thJC}	12.5	16	12.5	16	0/ ٧٧		

- a. Package limited.
- b. Surface mounted on 1" x 1" FR4 board.
- d. See solder profile (<u>www.vishay.com/doc?73257</u>). The PowerPAK SC-70 is a leadless package. The end of the lead terminal is exposed copper (not plated) as a result of the singulation process in manufacturing. A solder fillet at the exposed copper tip cannot be guaranteed and is not required to ensure adequate bottom side solder interconnection.
- e. Rework conditions: manual soldering with a soldering iron is not recommended for leadless components.
- Maximum under steady state conditions is 110 °C/W.

Document Number: 64832 S13-0463-Rev. B, 04-Mar-13 For technical questions, contact:: pmostechsupport@vishay.com

SiA517DJ

Vishay Siliconix



Parameter	Symbol	Test Conditions		Min.	Тур.	Max.	Unit			
Static				l	, ,,	l	<u>I</u>			
		V _{GS} = 0 V, I _D = 250 μA	N-Ch	12						
Drain-Source Breakdown Voltage	V_{DS}	V _{GS} = 0 V, I _D = - 250 μA	P-Ch	- 12			V			
V Tamanaratura Confficient	A) / /T	I _D = 250 μA	N-Ch		12		mV/°C			
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	I _D = - 250 μA	P-Ch		- 3.1					
V Tomporatura Coefficient	A)/ /T	I _D = 250 μA	N-Ch		- 2.5					
V _{GS(th)} Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	I _D = - 250 μA	P-Ch		2.4					
Cata Thurshald Valtage	V	$V_{DS} = V_{GS}, I_D = 250 \mu A$	N-Ch	0.4		1	V			
Gate Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_{D} = -250 \mu A$	P-Ch	- 0.4		- 1	V			
Gate-Body Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 8 \text{ V}$	N-Ch			± 100	nA			
date body Leakage	'655		P-Ch			± 100	ПА			
		$V_{DS} = 12 \text{ V}, V_{GS} = 0 \text{ V}$	N-Ch			1				
Zero Gate Voltage Drain Current	I _{DSS}	$V_{DS} = -12 \text{ V}, V_{GS} = 0 \text{ V}$	P-Ch			- 1	μΑ			
2010 Gate Voltage Blain Guirent	יטא	$V_{DS} = 12 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 55 ^{\circ}\text{C}$	N-Ch			10	μΑ			
		V_{DS} = - 12 V, V_{GS} = 0 V, T_{J} = 55 °C	P-Ch			- 10				
On State Prain Currentb	la,	$V_{DS} \ge 5 \text{ V}, V_{GS} = 4.5 \text{ V}$	N-Ch	15			Δ			
On-State Drain Current ^b	I _{D(on)}	$V_{DS} \le$ - 5 V, $V_{GS} =$ - 4.5 V	P-Ch	- 10			Α			
		$V_{GS} = 4.5 \text{ V}, I_D = 5 \text{ A}$	N-Ch		0.029					
		V _{GS} = - 4.5 V, I _D = - 3.6 A	P-Ch		0.050	0.061				
	R _{DS(on)}	$V_{GS} = 2.5 \text{ V}, I_D = 4.6 \text{ A}$	N-Ch		0.028	0.034				
		$V_{GS} = -2.5 \text{ V}, I_D = -3.2 \text{ A}$	P-Ch		0.066	0.081				
Drain-Source On-State Resistance ^b		$V_{GS} = 1.8 \text{ V}, I_D = 4.1 \text{ A}$	N-Ch		0.032	0.044	Ω			
		V _{GS} = - 1.8 V, I _D = - 1 A	P-Ch		0.093	0.115				
		$V_{GS} = 1.5 \text{ V}, I_D = 2 \text{ A}$	N-Ch		0.042	0.065				
		V _{GS} = - 1.5 V, I _D = - 1 A	P-Ch		0.112	0.170				
		$V_{DS} = 10 \text{ V}, I_{D} = 5 \text{ A}$	N-Ch		21		- S			
Forward Transconductance ^b	9 _{fs}	$V_{DS} = -10 \text{ V}, I_{D} = -3.6 \text{ A}$	P-Ch		11					
Dynamic ^a										
•			N-Ch		500					
Input Capacitance	C _{iss}	N-Channel	P-Ch		590		- pF			
Output Capacitance	C _{oss}	$V_{DS} = 6 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$	N-Ch		160					
Output Capacitance	Joss	P-Channel	P-Ch		280					
Reverse Transfer Capacitance	C _{rss}	$V_{DS} = -6 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$	N-Ch		100					
,			P-Ch		250					
		$V_{DS} = 6 \text{ V}, V_{GS} = 8 \text{ V}, I_{D} = 6.5 \text{ A}$	N-Ch		9.7	15	- - -			
Total Gate Charge	Q_{g}	$V_{DS} = -6 \text{ V}, V_{GS} = -8 \text{ V}, I_{D} = -4.5 \text{ A}$	P-Ch		13.1	20				
-	9	N-Channel	N-Ch		5.6	8.5				
	Q _{gs}	$V_{DS} = 6 \text{ V}, V_{GS} = 4.5 \text{ V}, I_{D} = 6.5 \text{ A}$	P-Ch		8.2	12.5	nC			
Gate-Source Charge			N-Ch P-Ch		0.72 1.2		-			
		P-Channel	N-Ch		0.74					
Gate-Drain Charge	Q_{gd}	$V_{DS} = -6 \text{ V}, V_{GS} = -4.5 \text{ V}, I_{D} = -4.3 \text{ A}$	P-Ch		2.8					
0.5.	-		N-Ch	0.7	3.5	7	-			
Gate Resistance	R_g	f = 1 MHz	P-Ch	2	10	20	Ω			

a. Guaranteed by design, not subject to production testing.

b. Pulse test; pulse width $\leq 300~\mu s,$ duty cycle $\leq 2~\%.$





SPECIFICATIONS (T _J = 25 °C, unless otherwise noted)											
Parameter	eter Symbol Test Conditions						Unit				
Dynamic ^a											
Turn-On Delay Time	t _{d(on)}	N-Channel	N-Ch		10	15					
<u> </u>	4(0.1.)	$V_{DD} = 6 \text{ V, R}_{I} = 1.2 \Omega$	P-Ch		30	40					
Rise Time	t _r	$I_D \cong 5.2 \text{ A}, V_{GEN} = 4.5 \text{ V}, R_q = 1 \Omega$	N-Ch		10	15					
		D = 0.1.1, 1 GEN 1, 1 · · · · ·	P-Ch		25	40					
Turn-Off Delay Time	t _{d(off)}	P-Channel	N-Ch P-Ch		22	30					
		$V_{DD} = -6 \text{ V}, R_{L} = 1.6 \Omega$	N-Ch		30 10	45 15					
Fall Time	t _f	$I_D \cong$ - 3.8 A, V_{GEN} = - 4.5 V, R_g = 1 Ω	P-Ch		_	_					
			N-Ch		20 5	30 10	ns				
Turn-On Delay Time	t _{d(on)}	N-Channel	P-Ch		8	15					
		$V_{DD} = 6 \text{ V}, R_{L} = 1.2 \Omega$	N-Ch		10	15					
Rise Time	t _r	$I_D \cong 5.2 \text{ A}, V_{GEN} = 10 \text{ V}, R_g = 1 \Omega$	P-Ch		12	20					
	t _{d(off)}	-	N-Ch		18	30					
Turn-Off Delay Time		P-Channel $V_{DD} = -6 \text{ V}, R_{L} = 1.6 \Omega$	P-Ch		25	40					
		$I_D \cong -3.8 \text{ A, V}_{GEN} = -10 \text{ V, R}_0 = 1 \Omega$	N-Ch		10	15					
Fall Time	t _f	1D = 0.07, VGEN = 10 V, Ng = 122	P-Ch		18	30					
Drain-Source Body Diode Characteristic	cs										
Continuous Source-Drain Diode Current	I _S	T _C = 25 °C	N-Ch			4.5	A				
Continuous Source-Diam Diode Current	'5	16-23-3	P-Ch			- 4.5					
Pulse Diode Forward Current ^a	I _{SM}		N-Ch			20					
Fulse blode Folward Current	-SIVI		P-Ch			- 10					
Body Diode Voltage	V_{SD}	$I_S = 5.2 \text{ A}, V_{GS} = 0 \text{ V}$	N-Ch		0.85	1.2	V				
Body Blode Voltage	*50	$I_S = -3.4 \text{ A}, V_{GS} = 0 \text{ V}$	P-Ch		- 0.8	- 1.2	, v				
Body Diode Reverse Recovery Time	t _{rr}		N-Ch		20	40	ns				
Body Blode Heverse Hecovery Time	٩r		P-Ch		30	60	110				
Body Diode Reverse Recovery Charge	Q _{rr}	N-Channel $I_F = 5.2 \text{ A}, \text{ dI//dt} = 100 \text{ A/}\mu\text{s}, T_J = 25 °C$	N-Ch		5	10	nC				
200, 2.000 Hoveroo Hoodwary Orlange	∀ rr	1- 0.2 /3, αι//αι = 100 /4/μο, 1j = 20 0	P-Ch		12	24	110				
Reverse Recovery Fall Time	ta	P-Channel	N-Ch		8		ns				
. is is is a final of the first	-а	$I_F = -3.8 \text{ A}, \text{ dI/dt} = -100 \text{ A/}\mu\text{s}, T_J = 25 ^{\circ}\text{C}$	P-Ch		16						
Reverse Recovery Rise Time	t _b		N-Ch		12						
	5		P-Ch		14						

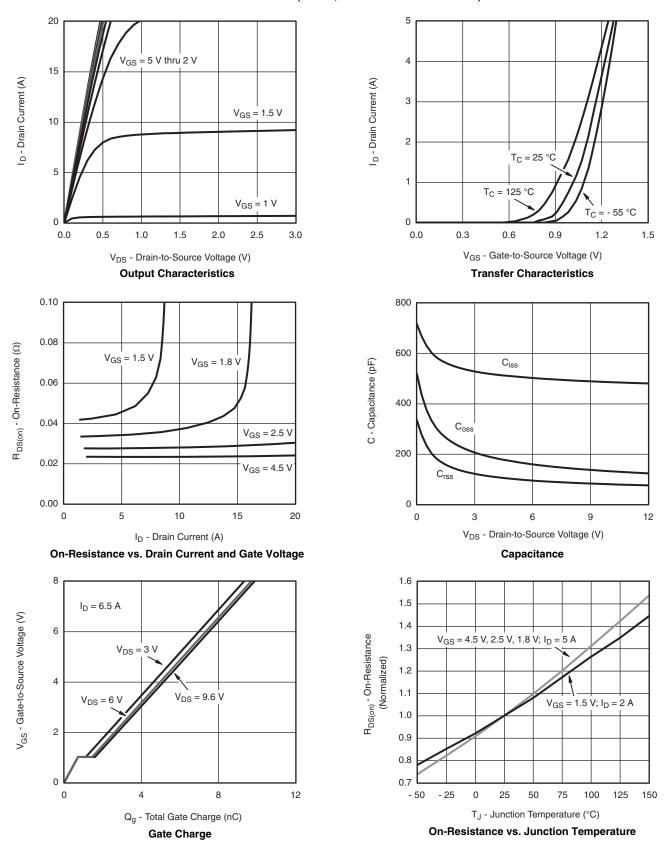
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

a. Guaranteed by design, not subject to production testing.

b. Pulse test; pulse width \leq 300 μ s, duty cycle \leq 2 %.

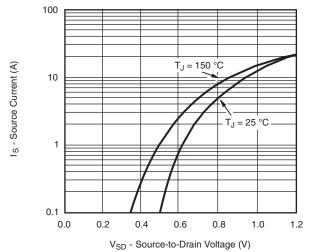


N-CHANNEL TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

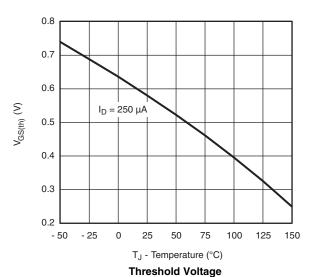


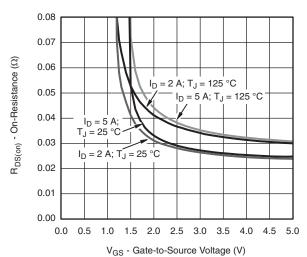


N-CHANNEL TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

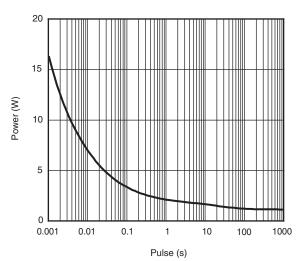


Source-Drain Diode Forward Voltage

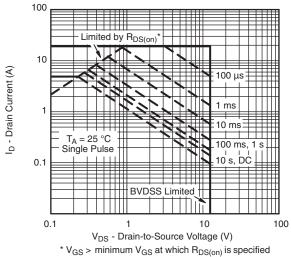




On-Resistance vs. Gate-to-Source Voltage



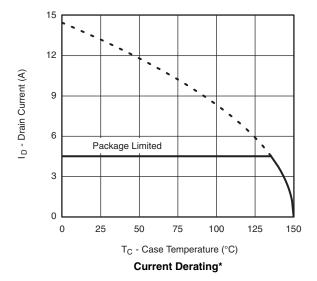
Single Pulse Power (Junction-to-Ambient)

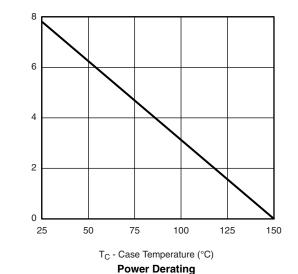


Safe Operating Area, Junction-to-Ambient



N-CHANNEL TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



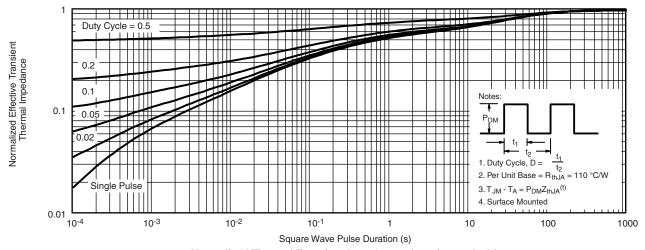


Power Dissipation (W)

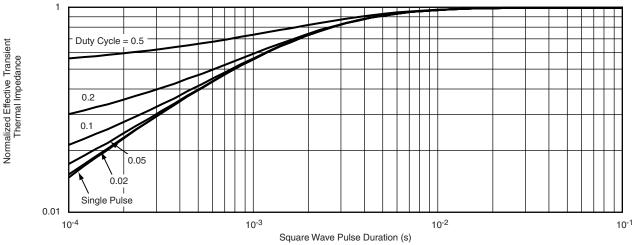
^{*} The power dissipation P_D is based on $T_{J(max.)}$ = 150 °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.



N-CHANNEL TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



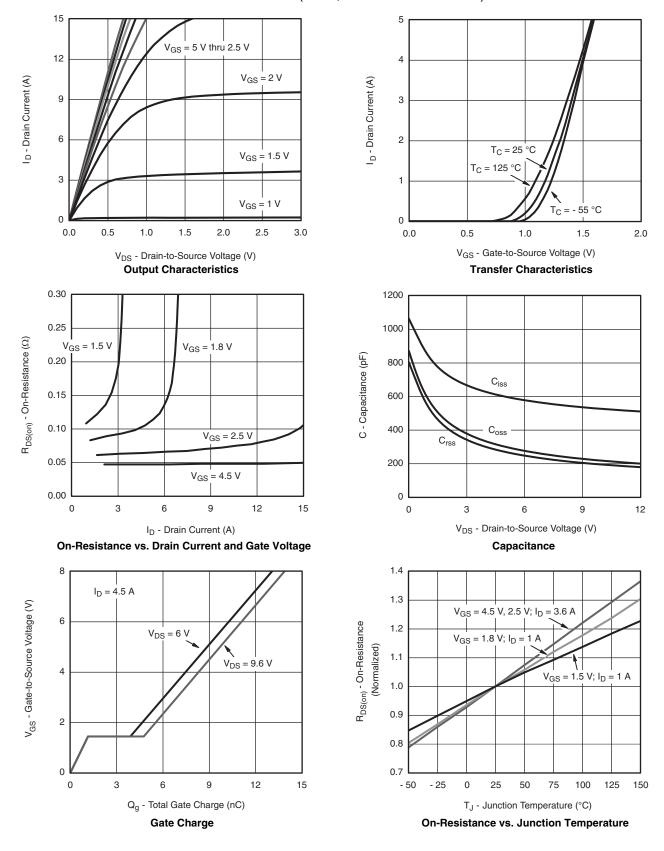
Normalized Thermal Transient Impedance, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Case

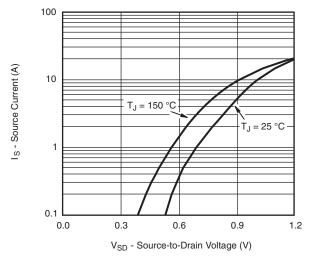


P-CHANNEL TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

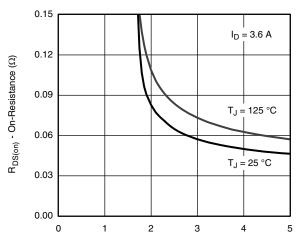




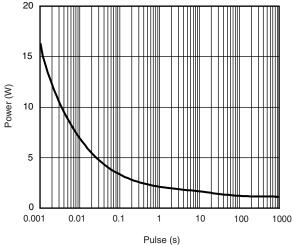
P-CHANNEL TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



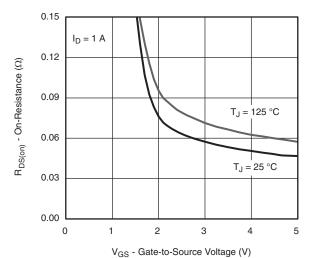
Soure-Drain Diode Forward Voltage



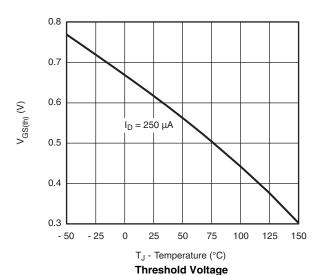
V_{GS} - Gate-to-Source Voltage (V) On-Resistance vs. Gate-to-Source Voltage



Single Pulse Power, Junction-to-Ambient



On-Resistance vs. Gate-to-Source Voltage

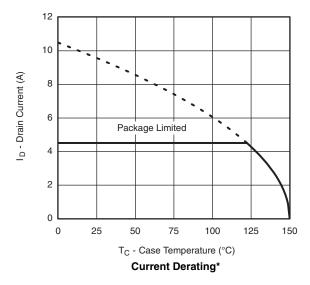


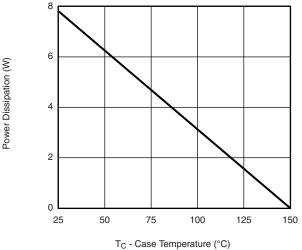
100 Limited by R_{DS(on)} I_D - Drain Current (A) T_A = 25 °C Single Pulse 0.1 **BVDSS** Limited 0.01 **L** 0.1 V_{DS} - Drain-to-Source Voltage (V) * V_{GS} > minimum V_{GS} at which $R_{DS(on)}$ is specified

Safe Operating Area, Junction-to-Ambient



P-CHANNEL TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



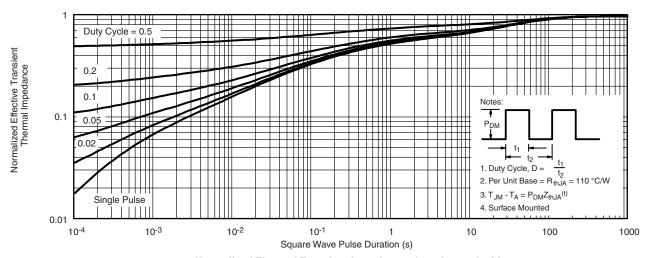


Power Derating

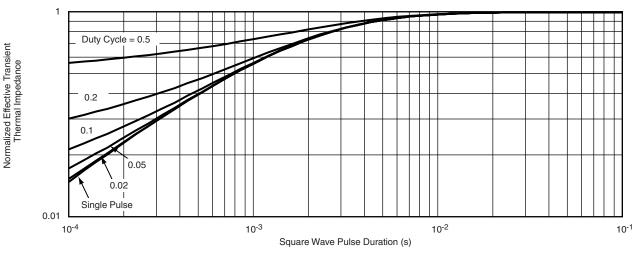
^{*} The power dissipation P_D is based on $T_{J(max.)}$ = 150 °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.



P-CHANNEL TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



Normalized Thermal Transient Impedance, Junction-to-Ambient



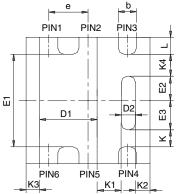
Normalized Thermal Transient Impedance, Junction-to-Case

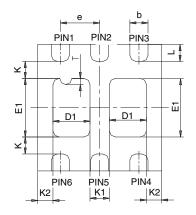
Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package/tape drawings, part marking, and reliability data, see www.vishay.com/ppg?64832.





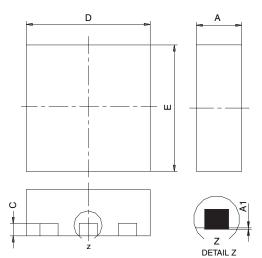
PowerPAK® SC70-6L





BACKSIDE VIEW OF SINGLE

BACKSIDE VIEW OF DUAL



- All dimensions are in millimeters
 Package outline exclusive of mold flash and metal burr
 Package outline inclusive of plating

			SINGL	E PAD			DUAL PAD					
DIM	M	ILLIMETER	RS		INCHES		M	ILLIMETER	RS		INCHES	
	Min	Nom	Max	Min	Nom	Max	Min	Nom	Max	Min	Nom	Max
Α	0.675	0.75	0.80	0.027	0.030	0.032	0.675	0.75	0.80	0.027	0.030	0.032
A1	0	-	0.05	0	-	0.002	0	-	0.05	0	-	0.002
b	0.23	0.30	0.38	0.009	0.012	0.015	0.23	0.30	0.38	0.009	0.012	0.015
С	0.15	0.20	0.25	0.006	0.008	0.010	0.15	0.20	0.25	0.006	0.008	0.010
D	1.98	2.05	2.15	0.078	0.081	0.085	1.98	2.05	2.15	0.078	0.081	0.085
D1	0.85	0.95	1.05	0.033	0.037	0.041	0.513	0.613	0.713	0.020	0.024	0.028
D2	0.135	0.235	0.335	0.005	0.009	0.013						
Е	1.98	2.05	2.15	0.078	0.081	0.085	1.98	2.05	2.15	0.078	0.081	0.085
E1	1.40	1.50	1.60	0.055	0.059	0.063	0.85	0.95	1.05	0.033	0.037	0.041
E2	0.345	0.395	0.445	0.014	0.016	0.018						
E3	0.425	0.475	0.525	0.017	0.019	0.021						
е		0.65 BSC			0.026 BSC			0.65 BSC			0.026 BSC	
K		0.275 TYP	1		0.011 TYP		0.275 TYP				0.011 TYP	
K1		0.400 TYP	1		0.016 TYP			0.320 TYP			0.013 TYP	
K2		0.240 TYP	1	0.009 TYP 0.252 TYP				0.010 TYP				
К3		0.225 TYP	1	0.009 TYP								
K4		0.355 TYP	1	0.014 TYP								
L	0.175	0.275	0.375	0.007	0.011	0.015	0.175	0.275	0.375	0.007	0.011	0.015
Т							0.05	0.10	0.15	0.002	0.004	0.006
ECNI- C C	7404 D	. 0 00 1	. 07									

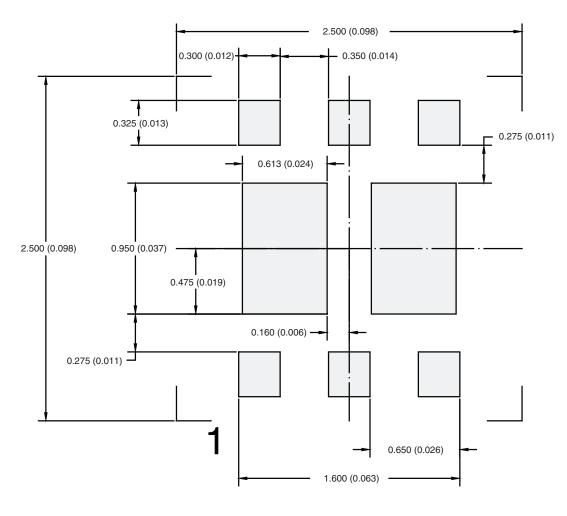
ECN: C-07431 - Rev. C, 06-Aug-07

DWG: 5934

Document Number: 73001 06-Aug-07



RECOMMENDED PAD LAYOUT FOR PowerPAK® SC70-6L Dual



Dimensions in mm (inches)

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Vishay

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Revision: 02-Oct-12 Document Number: 91000

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SIA517DJ-T1-GE3